

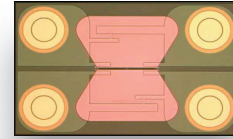
# GF705

## MagnetoResistive Magnetic Field Sensor

The GF705 is a magnetic field sensor based on the multilayer Giant MagnetoResistive (GMR) effect. The Sensor contains a Wheatstone bridge with on-chip flux concentrators to improve the sensitivity. The sensor is ideal for measuring magnetic fields in a linear range from 1.8 mT up to 8 mT.

A typical application is endpoint detection through a cylinder of stainless steel: A moving magnet inside a thick-walled cylinder is detected by a GF705 sensor from the outside.

The GF705 is available as bond version (bare die) and as flip-chip or LGA-package for SMD assembly.



### Product Overview GF708

Article description	Package	Delivery Type
GF708APA-AE	Flip-chip	Tape on reel (5000)
GF708ACA-AB	Die on wafer <sup>1)</sup>	Waferbox
GF708AKA-AC	SIL6	Waffle pack (90)
GF708AMA-AE	LGA6S	Tape on reel (2500)

<sup>1)</sup> Minimum order quantities apply.

### Quick Reference Guide

Symbol	Parameter	Min.	Typ.	Max.	Unit
V <sub>CC</sub>	Supply voltage	-	5.0	-	V
B <sub>Lin</sub>	Linear magnetic range	1.8	-	8.0	mT
S	Sensitivity (in linear range)	8	10	13	mV/V/mT
R <sub>b</sub>	Bridge resistance	4.0	5.0	7.0	ΩW

### Absolute Maximum Ratings

In accordance with the absolute maximum rating system (IEC60134).

Symbol	Parameter	Min.	Max.	Unit
V <sub>CC</sub>	Supply voltage	-9.0	+9.0	V
T <sub>amb</sub>	Ambient temperature	-40	+125	°C
T <sub>stg</sub>	Storage temperature	-65	+150	°C

Stresses beyond those listed under "Absolute maximum ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### Features

- Based on the GiantMagnetoResistive (GMR) effect
- Flip-chip assembly (BGA)
- Temperature range from -40 °C to +125 °C

### Advantages

- Large working distance
- Excellent absolute accuracy
- Large range of magnetic field strength
- Very small size
- Contactless field measuring
- Switching with adjustable switching thresholds

### Applications

- Endpoint detection in cylinders
- Reference monitoring
- Magnetic switches



### Magnetic Data

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$B_{Lin}$	Linear magnetic flux density range (abs)	See Fig.1	1.8	-	8.0	mT
$B_{sat}$	Saturation magnetic flux density <sup>1)</sup>	See Fig.1	-	±25	-	mT

<sup>1)</sup> At  $B_{sat}$  the sensor delivers the maximal output voltage  $V_{peak}$ . By exceeding the value of  $B_{sat}$  the output signal is no longer unique.

### Electrical Data

$T_{amb} = 25\text{ °C}$ ; unless otherwise specified.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$V_{CC}$	Supply voltage		-	5.0	-	V
S	Sensitivity	$B = (1.8...8)\text{ mT}$	8	10	13	mV/V/mT
$TC_S$	Temperature coefficient of Sensitivity <sup>2)</sup>	$T_{amb} = (-40...+125)\text{ °C}$	-0.26	-0.22	-0.18	%/K
$R_B$	Bridge resistance <sup>3)</sup>		4.0	5.0	7.0	k $\Omega$
$TC_{RB}$	Temperature coefficient of RB <sup>4)</sup>	$T_{amb} = (-40...+125)\text{ °C}$	0.17	0.20	0.23	%/K
$V_{peak}$	Maximum output voltage <sup>5)</sup>	See Fig.1	-	110	-	mV/V
f	Frequency range		1 <sup>6)</sup>	-	-	MHz

<sup>2)</sup>  $TC_S = 100 \cdot \frac{S_{(T_2)} - S_{(T_1)}}{S_{(T_1)} \cdot (T_2 - T_1)}$  with  $T_1 = 25\text{ °C}$ ;  $T_2 = 80\text{ °C}$ .

<sup>3)</sup> Bridge resistance between pads 1 and 3 and 2 and 4.

<sup>4)</sup>  $TC_{RB} = 100 \cdot \frac{R_{B(T_2)} - R_{B(T_1)}}{R_{B(T_1)} \cdot (T_2 - T_1)}$  with  $T_1 = 25\text{ °C}$ ;  $T_2 = 80\text{ °C}$ .

<sup>5)</sup> Maximal output voltage at  $B_{sat}$ .

<sup>6)</sup> No significant amplitude attenuation.

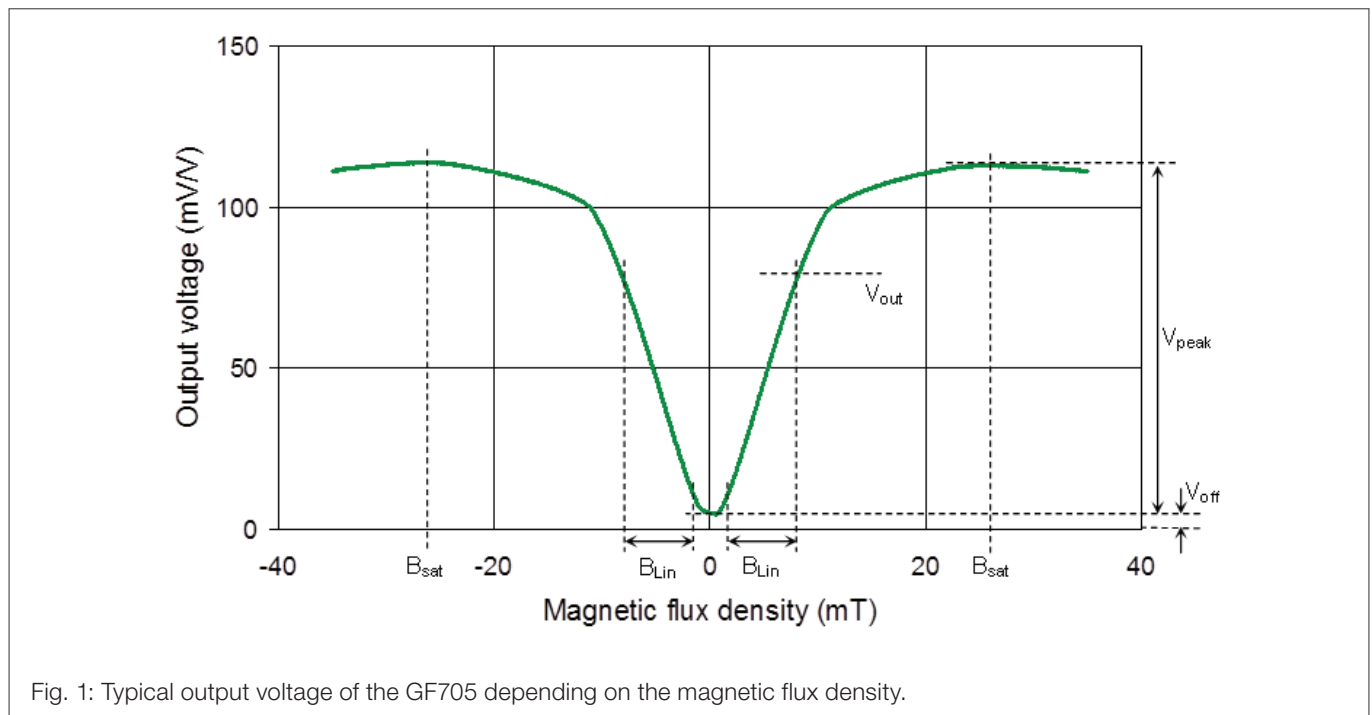


Fig. 1: Typical output voltage of the GF705 depending on the magnetic flux density.

**Accuracy**

$T_{amb} = 25\text{ }^\circ\text{C}$ ; unless otherwise specified.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$V_{off}$	Offset voltage per $V_{CC}$	See Fig. 1	-5.0	-	+5.0	mV/V
$TC_{Voff}$	Temperature coefficient of $V_{off}$	$T_{amb} = (-40\dots+125)\text{ }^\circ\text{C}$	-20	7	+25	$\mu\text{V/V/K}$
$\epsilon_{Lin}$	Linearity error	$B = (1.8\dots 8)\text{ mT}$ ; see Fig. 2	-	2	5	% of $V_{out}$
$H_C$	Hysteresis error <sup>1)</sup>	See Fig. 3	-	0.05	0.1	mT

<sup>1)</sup> The hysteresis error is ascertained in the magnetic field, ramped from 10 mT to -10 mT and back to 10 mT. The value is specified for the linear range  $B_{Lin}$ .

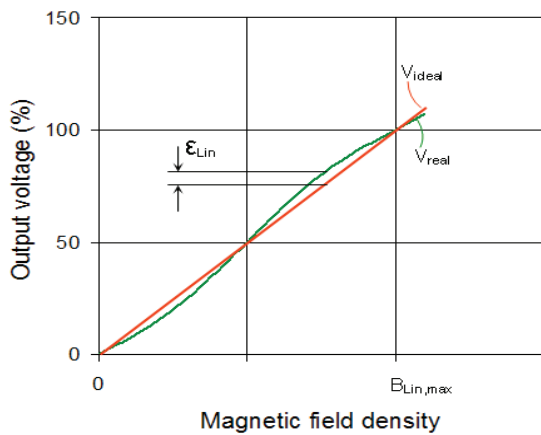


Fig. 2: Definition of linearity error  $\epsilon_{Lin}$  (schematic).

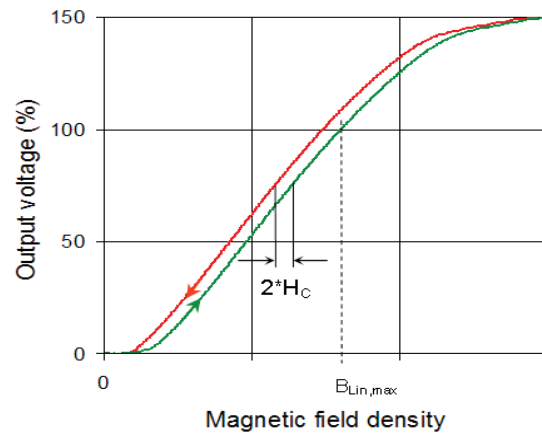


Fig. 3: Definition of hysteresis error  $H_C$  (schematic).

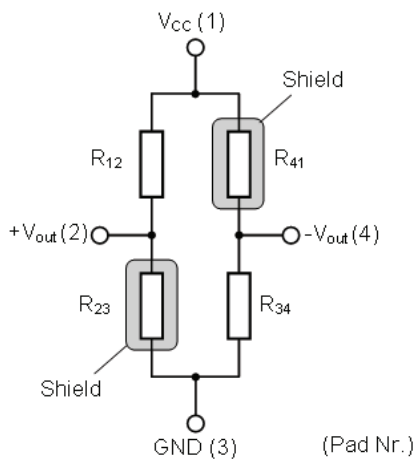


Fig. 4: Simplified circuit diagram.

In Fig. 4 the resistors  $R_{23}$  and  $R_{41}$  are covered by two flux concentrators (shields) to prevent an applied magnetic field from influencing them. Therefore, when a field is applied, the resistors  $R_{12}$  and  $R_{34}$  decrease in resistance, while the other two resistors under the flux concentrator do not. This imbalance leads to the bridge output.

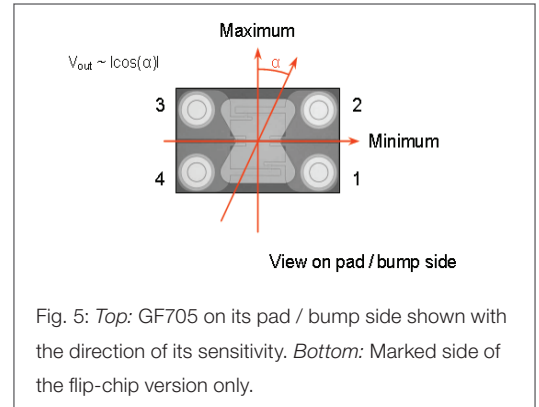
## GF705 as Bare Die and Flip-Chip

### Pinning

Pad	Symbol	Parameter
1	$V_{CC}$	Supply voltage
2	$+V_{out}$	Positive output voltage
3	GND	Ground
4	$-V_{out}$	Negative output voltage

Note:

Pin 1 is not marked on the chip. Since the chip is symmetrical, its orientation is only defined by its long and short side.

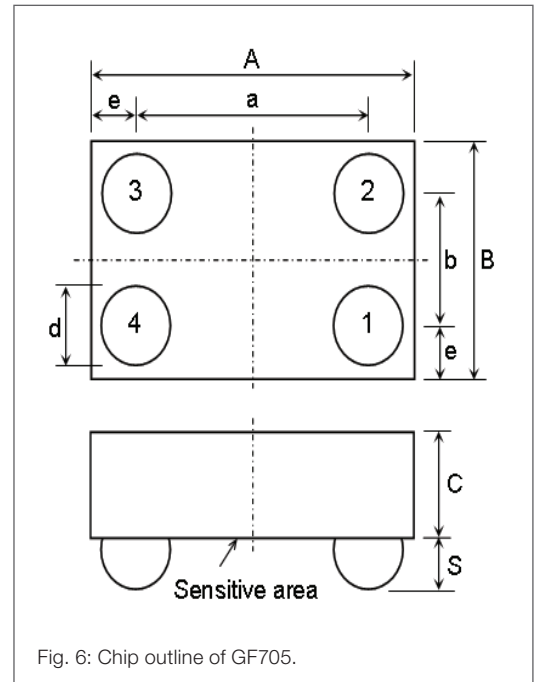


### Mechanical Data

Symbol	Parameter	Min.	Typ.	Max.	Unit	
A	Bare die	Length	1420	1460	1500	$\mu\text{m}$
		Width	920	960	1000	$\mu\text{m}$
		Height	240	250	260	$\mu\text{m}$
		Diameter	-	230	-	$\mu\text{m}$
A	Flip-chip	Length	1350	1400	1450	$\mu\text{m}$
		Width	850	900	950	$\mu\text{m}$
		Height	400	410	420	$\mu\text{m}$
		Diameter <sup>1)</sup>	-	300	-	$\mu\text{m}$
		Standoff <sup>2)</sup>	-	240	-	$\mu\text{m}$
a	Pitch a	-	1000	-	$\mu\text{m}$	
b	Pitch b	-	500	-	$\mu\text{m}$	
e	Margin	-	200	-	$\mu\text{m}$	

<sup>1)</sup> After reflow.

<sup>2)</sup> Diameter of solder ball before reflow.



### Data for Packaging and Interconnection Technologies

Symbol	Parameter	Conditions	Value	Unit
Bare die	Pad material		Au	-
	Pad thickness		0.4	$\mu\text{m}$
Flip-chip	Solder ball material		SnAg2.6Cu0.6	-
	Maximum solder temperature	For 6 s	260	$^{\circ}\text{C}$

**GF705AMA LGA6S**

**Pinning**

Pad	Symbol	Parameter
1	+V <sub>out</sub>	Positive output voltage
2	NC	Not connected
3	GND	Ground
4	V <sub>CC</sub>	Supply voltage
5	-V <sub>out</sub>	Negative output voltage
6-8	NC	Not connected

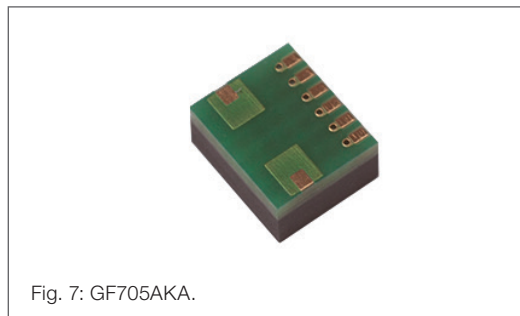


Fig. 7: GF705AKA.

**Dimensions**

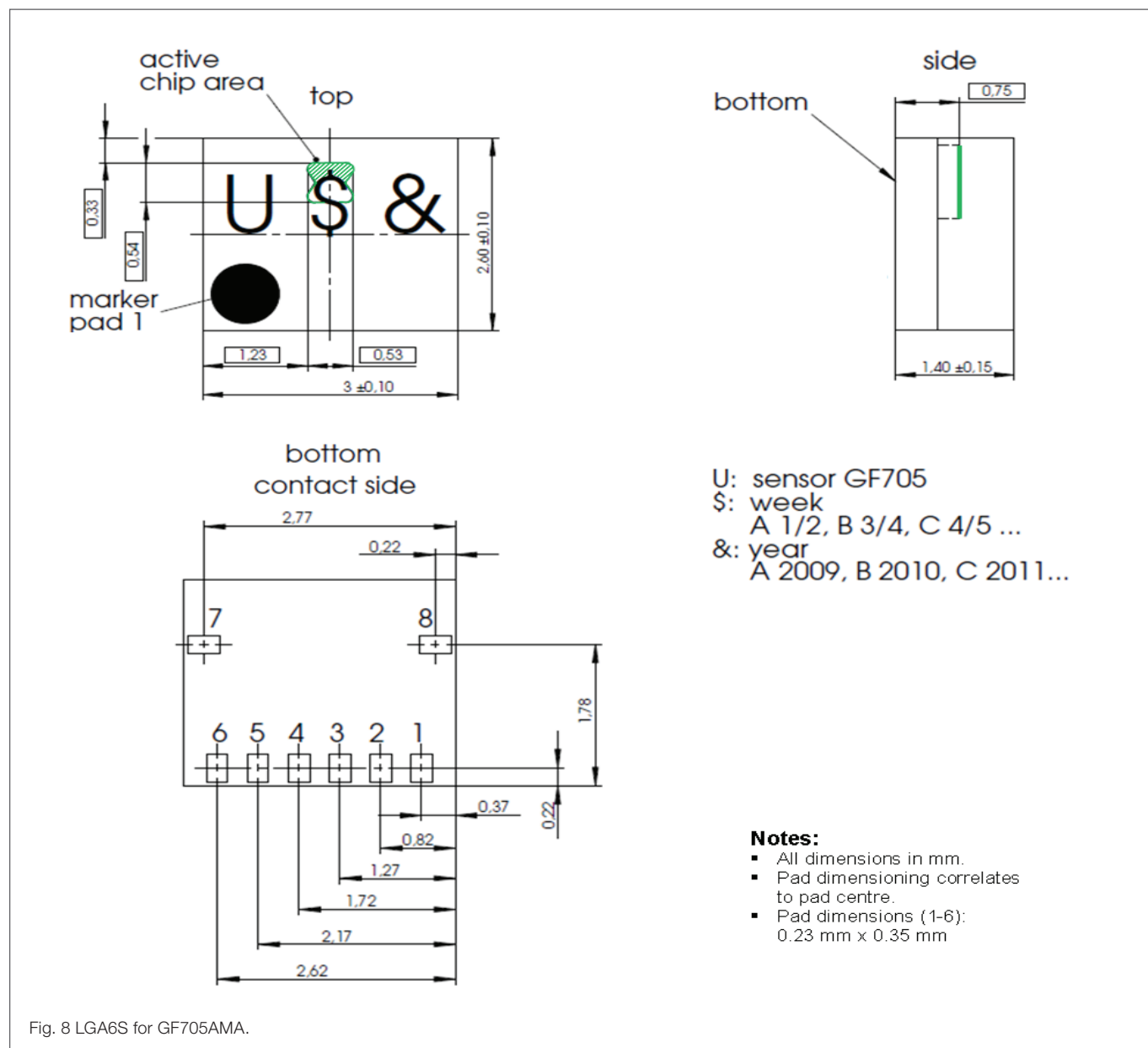


Fig. 8 LGA6S for GF705AMA.

## General Information

### Product Status

Article	Status
GF705APA-AB	The product is in series production.
GF705ACA-AB	The product is in series production.
GF705AMA-AE	The product is in series production.
<b>Note</b>	The status of the product may have changed since this data sheet was published. The latest information is available on the internet at <a href="http://www.sensitec.com">www.sensitec.com</a> .

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#### Sensitec GmbH

Georg-Ohm-Str. 11 · 35633 Lahnau · Germany  
 Tel. +49 6441 9788-0 · Fax +49 6441 9788-17  
[www.sensitec.com](http://www.sensitec.com) · [sensitec@sensitec.com](mailto:sensitec@sensitec.com)



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#### Sensitec GmbH

Georg-Ohm-Str. 11 · 35633 Lahnau · Germany  
Tel. +49 6441 9788-0 · Fax +49 6441 9788-17  
www.sensitec.com · sensitec@sensitec.com

